What is claimed is:

1. A multi layer ceramic electronic parts, comprising:

a laminated body in which a ceramic layer and internal electrodes and are laminated one another; and

external electrodes and being provided at end portions of the laminated body, in which the internal electrodes and opposing to each other reach to either one of at least a pair of edges of the ceramic layer, thereby leading out the internal electrodes and opposing to each other to either one of end surfaces of the laminated body, and connecting the internal electrodes and led out to the end surfaces of the laminated body to the external electrodes and, respectively, wherein pillar-like ceramic portions, being continuous in a direction of thickness of a conductor film forming the external electrodes and, are scattered in the conductor film.

2. A multi layer ceramic electronic parts as defined in the claim 1, wherein the ceramic portions contain a material common with ceramic material which forms the ceramic layer of the laminated body.

3. A multi layer ceramic electronic parts as defined in the claim 1 or 2, wherein the ceramic portions of the external electrodes and are so formed that they are continuous from an inner surface of the conductor film of the external electrodes and where it is closely contact with a surface of the laminated body up to a surface thereof.

4. A multi layer ceramic electronic parts as defined in any one of the claims 1 to 3, wherein the conductor film of each of the external electrodes and is made of at least one metal selected from a group consisting of Ni, Cu, Ag, Pd and Ag-Pd.

5. A multi layer ceramic electronic parts as defined in any one of the claims 1 to 4, wherein the external electrodes and are baked at same time of baking the laminated body.

6. A method for manufacturing a multi layer ceramic electronic parts, comprising: a laminated body in which a ceramic layer and internal electrodes and are laminated one another; and external electrodes and being provided at end portions of the laminated body, in which the internal electrodes and opposing to each other reach to either one of at least a pair of edges of the ceramic layer, thereby leading out the internal electrodes and opposing to each other to either one of end surfaces of the laminated body, and connecting the internal electrodes and led out to the end surfaces of the laminated body to the external electrodes and, respectively, wherein comprising following steps of:

preparing the laminated body being unbaked;

applying and drying a conductor paste, into which is added a material common with a ceramic forming the ceramic layers of the laminated body with a conductor powder, on the edge portions of the unbaked laminated body;

forming the external electrodes and so that they are conducted with the internal electrodes and at the end surfaces of the laminated body, by baking the laminated body; and

completing the multi layer ceramic electronic parts.

7. (New) A method for manufacturing a multi-layer ceramic electronic part, said multi-layer ceramic electronic part comprising a laminated body in which a ceramic layer and internal electrodes are laminated on one another, external electrodes provided at end portions of the laminated body, the internal electrodes opposing each other and reaching to one of at least a pair of edges of the ceramic layer, thereby leading out the internal electrodes to an end surface of the laminated body and connecting the internal electrodes to the external electrodes, and pillar-like ceramic portions which are continuous in a direction of thickness of a conductor film forming the external electrodes and scattered in the conductor film, said method comprising the steps of:

preparing an unbaked laminated body comprising a ceramic layer and internal electrodes laminated on one another;

applying and drying a conductor paste, into which is added a material common with a ceramic forming the ceramic layer of the laminated body, on edge portions of the unbaked laminated body;

forming external electrodes in contact with the internal electrodes at end surfaces of the laminated body;

baking the laminated body; and

completing the multi-layer ceramic electronic part.

8. (New) The method of Claim 7, additionally comprising the step of providing pillar-like ceramic portions which are scattered in a conductor film forming the external electrodes and continuous in a direction of thickness of the conductor film.

9. (New) The method of Claim 7, additionally comprising the step of forming the ceramic portions of the external electrodes so that they are continuous from an inner surface of the conductor film of the external electrodes, where it closely contacts with a surface of the laminated body, up to an outer surface thereof.

10. (New) The method of Claim 7, additionally comprising the step of forming the conductor film of at least one metal selected from the group consisting of Ni, Cu, Ag, Pd and an Ag-Pd alloy.